SMD REWORK TECHNOLOGY
All MARTIN rework systems utilize advanced convection and infrared heating technologies, delivering extremely repeatable and efficient heating. HD vision provides high contrast and pin sharp images.

Component alignment and placement is effortless and accurate, performed automatically via AVP package recognition. New APP Tools support flux dipping, solder paste printing solutions along with the presentation of the smallest μSMD.

**Martin technologies**

**Hybrid from below**

Using the advantages of both convection and infra-red technologies, energy is transferred efficiently with uniform heat distribution across the PCB. Controlled heating and cooling of small and large mass assemblies, minimize temperature induced stresses and preheat products for optimized soldering.

**Clear Vision**

The EXPERT 10.6 vision system displays HD quality images for precise alignment. High-quality optical systems are available for a wide range of applications from μSMDs to large components. The Auto-Lens-Detect function eliminated all vision calibration.

**New APP Tools**

DIPPING, PRINTING, HANDLING are supported by the new APP TOOL feature. Whether flux dipping, printing QFNs or presenting μSMDs for placement - all can be accomplished quickly, precisely and without programming.

**Soldering tools**

Advanced technologies such as thermal imaging provide optimal nozzle designs to ensure maximum thermal uniformity and heat transfer for all MARTIN rework systems.

The specific MARTIN nozzle designs provides maximum thermal isolation of adjacent components.
EXPERT 10.6

Extensive tasks.

The EXPERT 10.6 rework platform delivers reliable and precise rework of surface mount devices, sockets and connectors. Innovative technologies such as Advanced Vision Placement (AVP) provide repeatable component alignment and soldering automatically, minimizing operator reliance. Ultra-flexible product support features simplify top-justified PCB positioning. All 10.6 systems are configured for residual solder removal and dispensing of flux or solder paste.

Top Features

Camera-supported rework

- **Flexibility**
  Various PCB sizes and shapes as well as components available up to 75 x 75 mm²

- **Multifunctionality**
  One device for all processes, including desoldering, pad cleaning, automatic positioning and soldering

- **Under-heating system**
  Large PCBs 500 x 500 mm²

- **Process control**
  Automatic profiler for under- and top-heating systems

- **Performance**
  Uniform heat distribution through convection and hybrid technology

- **Software**
  Simple, intuitive, tablet-compatible
EASYSOLDER 07

Intuitive Design.

The software EASYSOLDER 07 guides the user through the entire rework process with clarity. The “AutoProfiler” is a special simplification. Using a few datapoints and the measured values of several temperature sensors, the software module creates a soldering and desoldering profile.

Each process step can be saved, edited and reloaded later. The functions are arranged very clearly and can be used intuitively. For documentation purposes and Industry 4.0 standards, the report function enables the creation of protocols and analyses of the results. EASYSOLDER 07 can be used by all touch-enabled laptops or tablets.

EASYSOLDER 07 functions:

- Desoldering of various components
- Removal of old solder from printed circuit boards
- Dispensing new solder paste or flux
- Placement of new components
- Soldering of new components
- Touch-enabled software interface

Intuitive Design
permanent control of all parameters

RELIABLE PROCESS
AUTOPROFILER for all applications

EASY HANDLING
flexible stand with magnet power
EXPERT 05.6

Manual tasks.

The Rework station with 2,000 W heating power in IR technology allows uniform heating over an area of 185 x 245 mm² and prevents mechanical stress due to temperature differences during the process. The high-resolution camera delivers fast, accurate and reproducible placement results. Even the smallest components from a size of 1 x 1 mm² can be repaired and placed. User-friendly handling is provided by the touch-enabled EASYSOLDER 07 software. Reflow profiles with individual temperature parameters can be created, edited and saved and enable high process reliability and repeatable soldering. The Expert 05.8 IXH is a precise, cost-effective solution for the complete rework process on one unit.

Top Features

- **Flexibility**
  - Various PCB sizes and shapes as well as components available

- **Precision**
  - Precise camera-supported placement

- **Under-heating system**
  - IR heating system, variable heating area

- **Software**
  - Simple, intuitive, tablet-compatible

- **Multifunctionality**
  - One device for all processes, including desoldering, pad cleaning, camera-supported positioning and soldering

- **Plug and Play**
  - Compact format, innovative design and intuitive operation for professional manual rework
HOTBEAM 05
High performing under heater in IR technology.

This Hotbeam is perfectly suitable for hand soldering tasks. The under-heating system can be used simply and comfortably in the various operating modes (consistent power, consistent temperature and profile) via the intuitive menu navigation. The innovative heating-management system ensures a reproducible circuit board temperature without overshooting at the highest long-term stability. The Auto-Profiler feature determines required device settings (profile) automatically for the user. The exact desired circuit board temperature is attained by executing the profile learned automatically by the device. Working processes become safer and more efficient. The IR lamps, which are protected by a glass plate, are independently switchable. This makes cleaning of the hot area easy and simple. Furthermore, the under-heating system can control devices (e.g. for removal by suction) or configure them in such a way that they become activated by external devices (SPS or foot switches). The EASYBEAM software allows for the sorting, editing and writing of profiles via a USB connection.

Top Features
Precise preheating

- **Format**
  Flexibility in terms of the circuit board’s shape and size: up to 200 x 250 mm are able to be processed

- **Flexibility**
  Preheating circuit board for the subsequent Rework process, through to curing and cracking of underfill

- **Process control**
  Use of temperature profiles via PC software

- **Process reliability**
  Various operating modes, e.g. for consistent power, consistent temperature and profiles

- **Performance**
  HOTBEAM and SMART DESOLDER combination for the perfect rework

- **Ergonomic workstation**
  Table mount available
MINIOVEN 05

Precision and quality.

The robust design of the MINIOVEN 05 offers integrated features such as convection circulation, infrared heating source, process gas distribution and a user-friendly operator interface. This configuration yields an optimal Reballing and Prebumping system, heating is extremely uniform across the device.

The use of nitrogen process gas ensures a soldering atmosphere where oxidation is minimised and promotes optimal wetting of solder joints as well as increased component life expectancy.

Top Features

Hybrid heating technology for the best temperature distribution

- **Process reliability**
  Optimized heat distribution via convection

- **Flexibility**
  Reflow of solder paste or solder balls

- **Plug and Play**
  Compact format, innovative design and intuitive operation

- **Precision**
  Nitrogen connection for optimal reflow of solder balls

- **Process control**
  Use of temperature profiles via PC software

- **Support**
  Tailored mask design
SMART DESOLDER 01
Removing residual solder.

The SMART DESOLDER 01 combines a manual hot gas source with a vacuum pen. The remaining solder on the board or on the BGA can be heated systematically and be removed by the vacuum pen. Due to this gentle procedure damages on the boards caused by overheating or mechanical stress can be avoided.

Top Features
Manual hot-gas source with a vacuum pen

- **Process safety**
The soft and antistatic Teflon tip prevents damage to the pads through high mechanical or electrical demands

- **Plug and Play**
Compact format, innovative design and intuitive operation

- **Temperature control**
The temperature-controlled airflow prevents the pads from overheating as well as neighboring components from heating up

- **Process control**
Solder pen's controlled airflow between 5–25 l/min

- **Performance**
HOTBEAM and SMART DESOLDER combination for the perfect rework

- **Flexibility**
Intuitive use, with two handheld pens